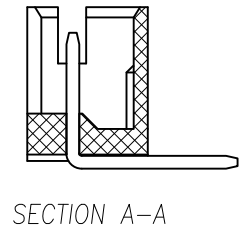
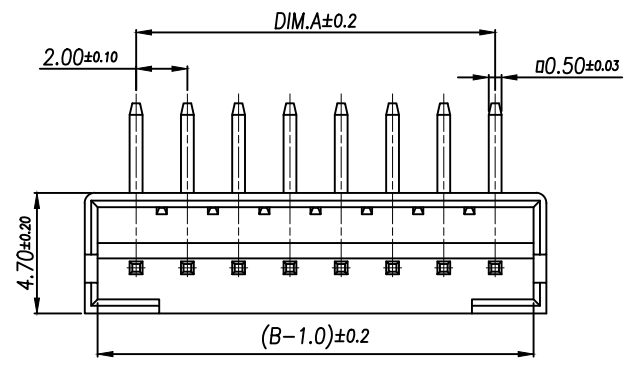
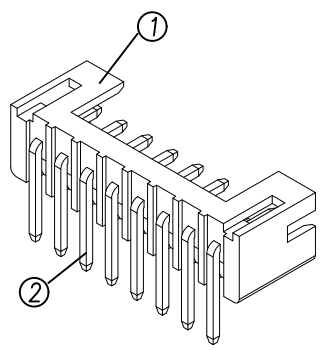
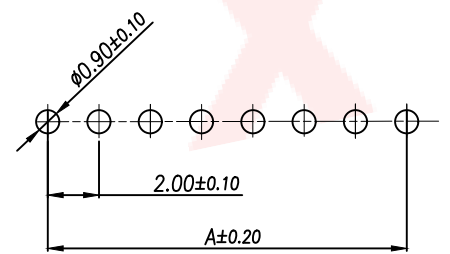
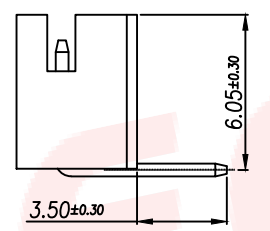
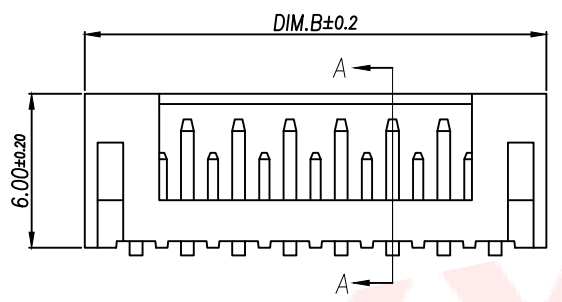


PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



- 技术要求:
1. 塑件材料: PA66 (UL-94V-0)
 2. 接触件: 黄铜镀锡
 3. 接触电阻: $\leq 10m\Omega$
 4. 绝缘电阻: $\geq 1000M\Omega$
 5. 额定电压: 250V AC DC
 6. 额定电流: 2.0A AC DC
 7. 耐压: 能承受 1000V AC/Min ute
 8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
 9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $220\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
 10. 铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B
XY-PH2.0-2AW-C	2	2	6
XY-PH2.0-3AW-C	3	4	8
XY-PH2.0-4AW-C	4	6	10
XY-PH2.0-5AW-C	5	8	12
XY-PH2.0-6AW-C	6	10	14
XY-PH2.0-7AW-C	7	12	16
XY-PH2.0-8AW-C	8	14	18
XY-PH2.0-9AW-C	9	16	20
XY-PH2.0-10AW-C	10	18	22
XY-PH2.0-11AW-C	11	20	24
XY-PH2.0-12AW-C	12	22	26
XY-PH2.0-13AW-C	13	24	28
...
XY-PH2.0-20AW-C	20	(20-1)*2	(20+1)*2



2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED		TITLE: WAFER 2.0mm H6.0mm 90° DIP		
.X±0.35	X.*± 5°	APR.	Alex	DWG NO. XY-PH2.0-NAW-C
.XX±0.25	.X.*± 3°	CHK.	Jack	PROJ. CUSTOMER DRAWING
.XXX±0.15	.XX.*± 1°	DRA.	Can	SIZE A4 SCALE 1:1 SHEET 1/1 REV. A